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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : **Confirmation No. 7353**
Tetsuji TOGAWA et al. : Attorney Docket No. 2005_1890A
Serial No. 10/559,135 : Group Art Unit 3723
Filed February 11, 2008 : Examiner Eileen P. Morgan

SUBSTRATE POLISHING APPARATUS
AND SUBSTRATE POLISHING METHOD

RESPONSE

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

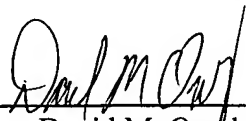
Sir:

Pursuant to the requirement contained in the Office Action mailed September 22, 2008, Applicants hereby elect invention I, claims 1-14, drawn to a method and apparatus for polishing a substrate.

In view of this election, a full examination on the merits of the present application is respectfully requested.

Respectfully submitted,

Tetsuji TOGAWA et al.

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